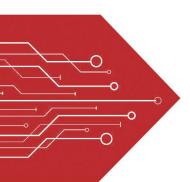
MSKSEMI















ESD

TVS

TSS

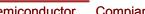
MOV

GDT

PLED

Broduct data sheet









SMC

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Fast switching speed

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.21 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwies specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

D/N/MADIZ)	DCEA	DCED	DCED	DCEC	DCEL	DCEI	DCEM	
P/N(MARK)	RS5A	RS5B	RS5D	RS5G	RS5J	RS5K	RS5M	UNITS
Maximum Recurrent Peak Reverse Voltage		100	200	400	600	800	1000	V
Maximum RMS Voltage		70	140	280	420	560	700	V
Maximum DC Blocking Voltage		100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current								
at Ta=75°C	5.0			Α				
Peak Forward Surge Current, 8.3 ms single half sine-wave								
superimposed on rated load (JEDEC method) 150			Α					
Maximum Instantaneous Forward Voltage at 5.0A	1.3		V					
Maximum DC Reverse Current Ta=25°C	t Ta=25°C 5.0		μΑ					
at Rated DC Blocking Voltage Ta=125°C	350		μА					
Maximum Reverse Recovery Time (Note 1)		15	50		250	50	00	nS
Typical Junction Capacitance (Note 2) 70			pF					
Operating and Storage Temperature Range TJ, Tstg		-65—+150				°C		

NOTES:

- 1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
- 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

RATING AND CHARACTERISTIC CURVES (RS5A THRU RS5M)

FIG.1-TYPICAL FORWARD

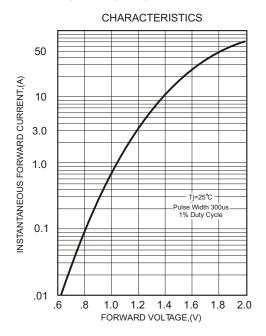
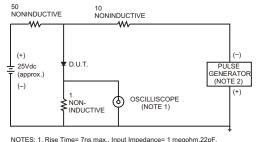


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= /ns max., Input Impedance= 1 megohm.22pf

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

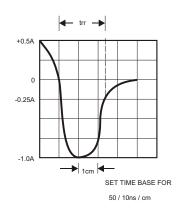


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

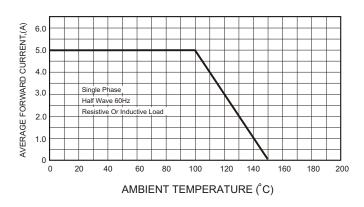


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

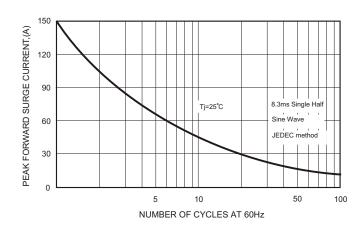
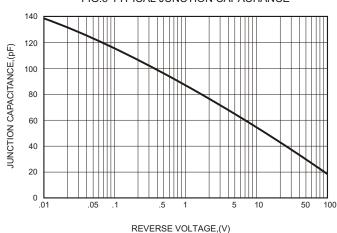
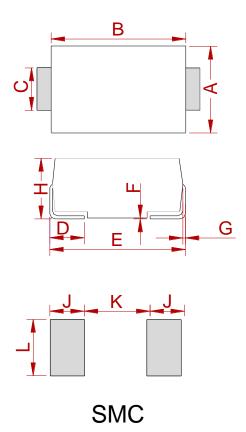


FIG.5-TYPICAL JUNCTION CAPACITANCE





PACKAGE MECHANICAL DATA



	Dimensions					
Ref.	Millimeters		Inches			
	Min.	Max.	Min.	Max.		
Α	5.75	6.25	0.226	0.246		
В	6.90	7.40	0.272	0.291		
С	2.75	3.25	0.108	0.128		
D	0.95	1.52	0.037	0.060		
E	7.70	8.20	0.303	0.323		
F	0.051	0.203	0.002	0.008		
G	0.15	0.31	0.006	0.012		
Н	2.15	2.62	0.085	0.103		
J	2.40		0.094			
K		4.20		0.165		
L	3.30		0.130			

REEL SPECIFICATION

P/N	PKG	QTY
RS5A THRU RS5M	SMC	3000



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